



**REPUBLIC OF SINGAPORE
THE PATENT ACT (CHAPTER 221)
CERTIFICATE ISSUED UNDER SECTION 35**

I HEREBY CERTIFY that under the provisions of the Patent Act, a patent has been granted in respect of an invention having the following particulars:

TITLE : METHOD AND APPARATUS FOR SOLDER BALL
PLACEMENT

**APPLICATION NUMBER/
PATENT NUMBER** : 10201508043V

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PRIORITY DATA : -

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DATED THIS 19TH DAY OF FEBRUARY 2020



Daren Tang Heng Shim
Registrar of Patents
Singapore